

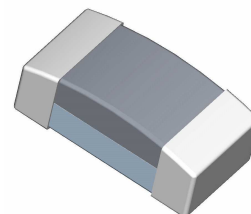
**Specification Status: Released**

**BENEFITS**

- ESD protection for high frequency applications (HDMI 1.3)
- Smaller form factor for board space savings
- Helps protect electronic circuits against damage from electrostatic discharge (ESD) events
- Assists equipment to pass IEC 61000-4-2, level 4 testing

**FEATURES**

- 0.25 pF (typ) Capacitance
- Low leakage current
- Low clamping voltage
- Fast response time (<1ns)
- Capable of withstanding numerous ESD strikes
- Compatible with standard reflow installation procedures
- Thick film technology
- Bi-directional protection



**APPLICATIONS**

- HDMI 1.3 interface
- LCD, HDTV
- Cellular phones
- Antennas (cell phones, GPS...)
- Portable video devices (PDA, DSC, Bluetooth...)
- Printer ports
- High speed Ethernet
- USB 2.0 and IEEE 1394 interfaces
- DVI interface

**CAUTION:** This device should not be used in Power Bus applications

**MATERIALS INFORMATION**

**RoHS Compliant**

Directive 2002/95/EC  
Compliant

**ELV Compliant**

Directive 2000/53/EC  
Compliant

**Halogen Free\***



**PART NUMBERING**

Series PESD 0402 - 140 Operating Voltage Designator  
EIA Size                       $14 \times 10^0 = 14V_{DC}$

\* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm

## ESD Protector Overvoltage Protection Device

PRODUCT: PESD0402-140

DOCUMENT: SCD27440  
REV LETTER: D  
REV DATE: MAY 10, 2011  
PAGE NO.: 2 OF 9

### TYPICAL DEVICE RATINGS AND CHARACTERISTICS

	Continuous Max Operating Voltage	Typical TLP Trigger Voltage <sup>1</sup>	Typical TLP Clamping Voltage <sup>1</sup> after 30ns	Typical Capacitance <sup>2</sup> @ 1 MHz, 1V <sub>rms</sub>	Typical Leakage Current @14V <sub>DC</sub>	Max Leakage Current @14V <sub>DC</sub>
Symbol	V <sub>DC</sub>	V <sub>T(TLP)</sub>	V <sub>C(TLP 30)</sub>	C <sub>p</sub>	I <sub>L(Typ)</sub>	I <sub>L(MAX)</sub>
Unit	V	V	V	pF	μA	μA
Value	14	250	40	0.25	<0.01	10.0

Note 1: TLP test method at 1000V (refer to FIG. 5 on page 5)

Note 2: Typical capacitance @ 0V and 14V bias

### GENERAL CHARACTERISTICS

Operating temperature: -55°C to +125°C

Storage temperature: -40°C to +85°C

ESD voltage capability (tested per IEC 61000-4-2)

- Contact discharge mode: 8kV (typ), 15kV (max)
- Air discharge mode: 15kV (typ), 25kV (max) [1 pulse: per customer request]

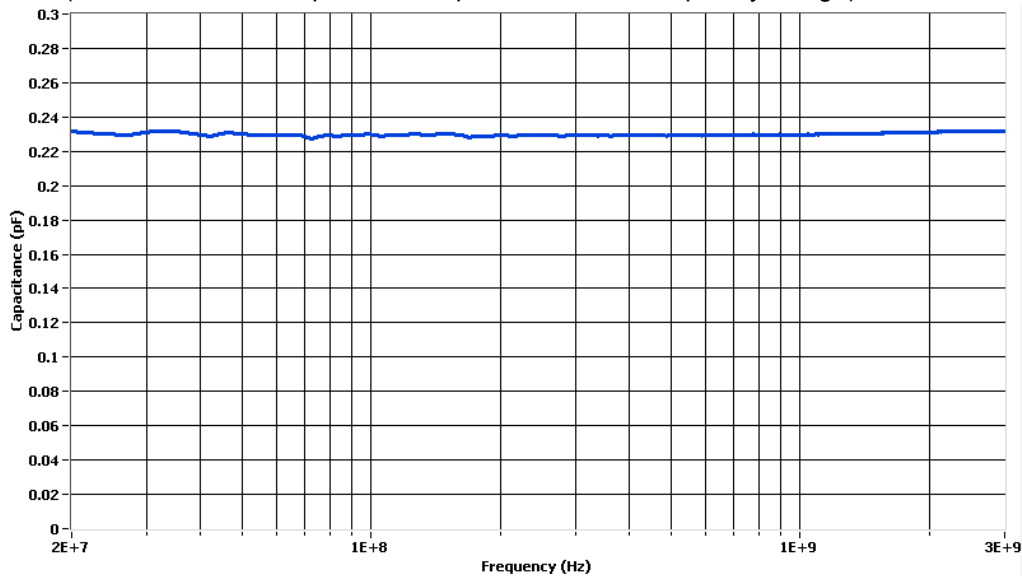
ESD pulse withstand: Typically 100 pulses (tested per IEC 61000-4-2, level 4, and contact method)

### Environmental Specifications

	Bias Humidity Test	Thermal Shock	Bias Heat Test	Bias Low Temp Test	Solderability	Solder Heat	Vibration	Mechanical Shock	Solvent Resistance
Test Conditions	@ 85°C @ 85% RH V <sub>DC</sub> (max) 1000 hours	-55°C to 125°C 30min dwell 1000 cycles	@ 125°C V <sub>DC</sub> (max) 1000 hours	@ -55°C V <sub>DC</sub> (max) 1000 hours	250 °C +/- 5°C 3s +/- 1s	260 °C, 10s	10 to 50Hz, 60s cycle, 2hrs each in X-Y-Z axis	1500G, 0.5ms, X-Y-Z axis 3 times	IPA ultrasonic 300s
Pass/Fail Criteria	I <sub>L</sub> ≤ 10μA	I <sub>L</sub> ≤ 10μA	I <sub>L</sub> ≤ 10μA	I <sub>L</sub> ≤ 10μA	95% coverage	90% coverage	No Physical Damage I <sub>L</sub> ≤ 10 μA	No Physical Damage I <sub>L</sub> ≤ 10 μA	No Physical Damage I <sub>L</sub> ≤ 10 μA

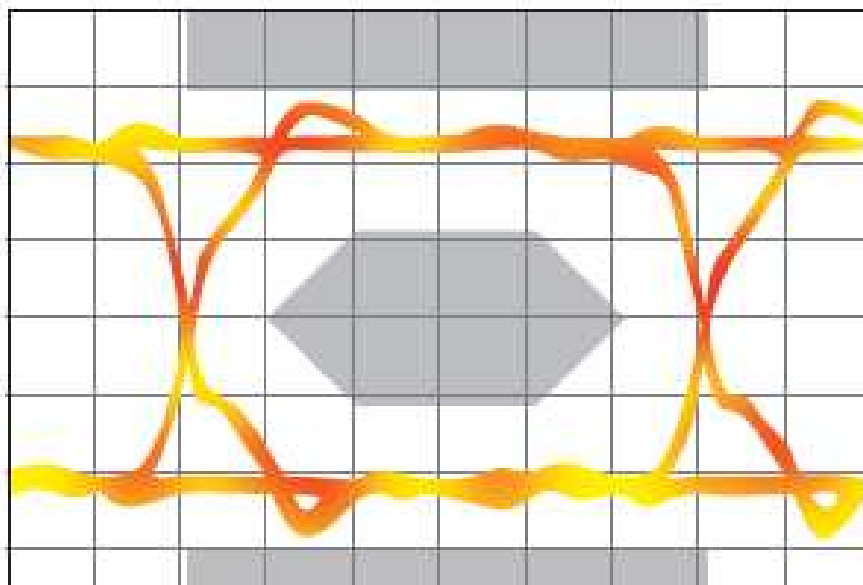
**FIG 1: CAPACITANCE VS. FREQUENCY (TYPICAL SAMPLE)**

(PESD0402 Flat Response of Capacitance over Frequency Range)



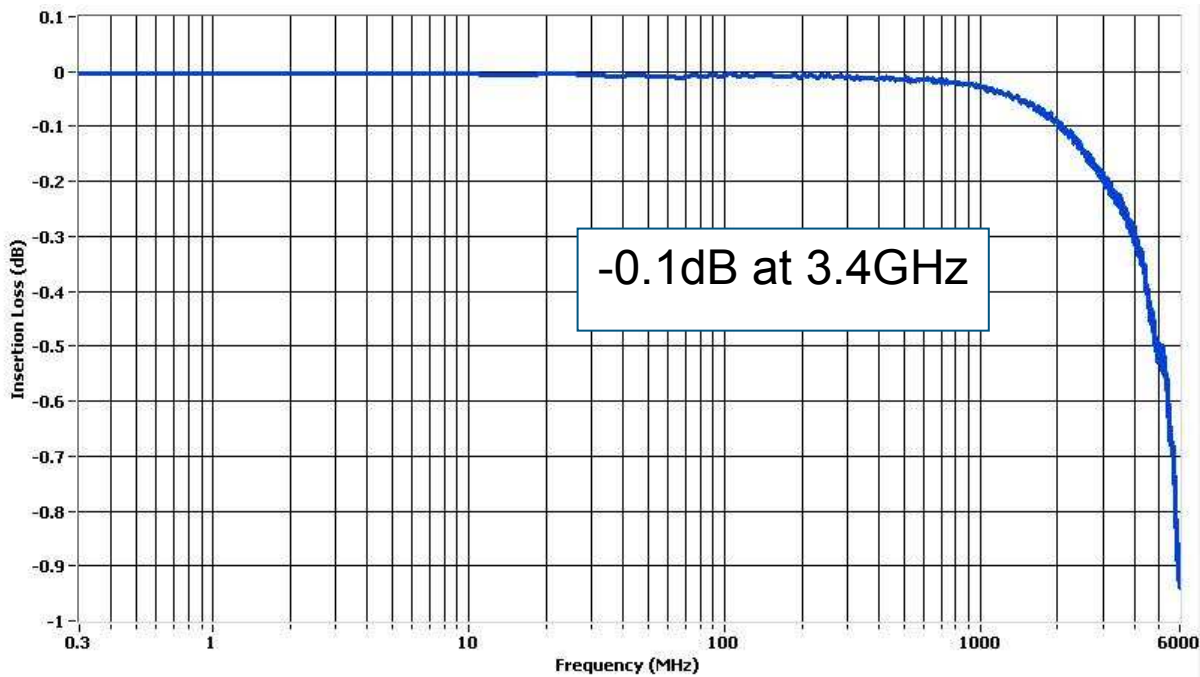
**FIG 2: EYE DIAGRAM (TYPICAL SAMPLE)**

(PESD0402 Eye Diagram Performance at 3.4 GHz— meets criteria for HDMI 1.3)



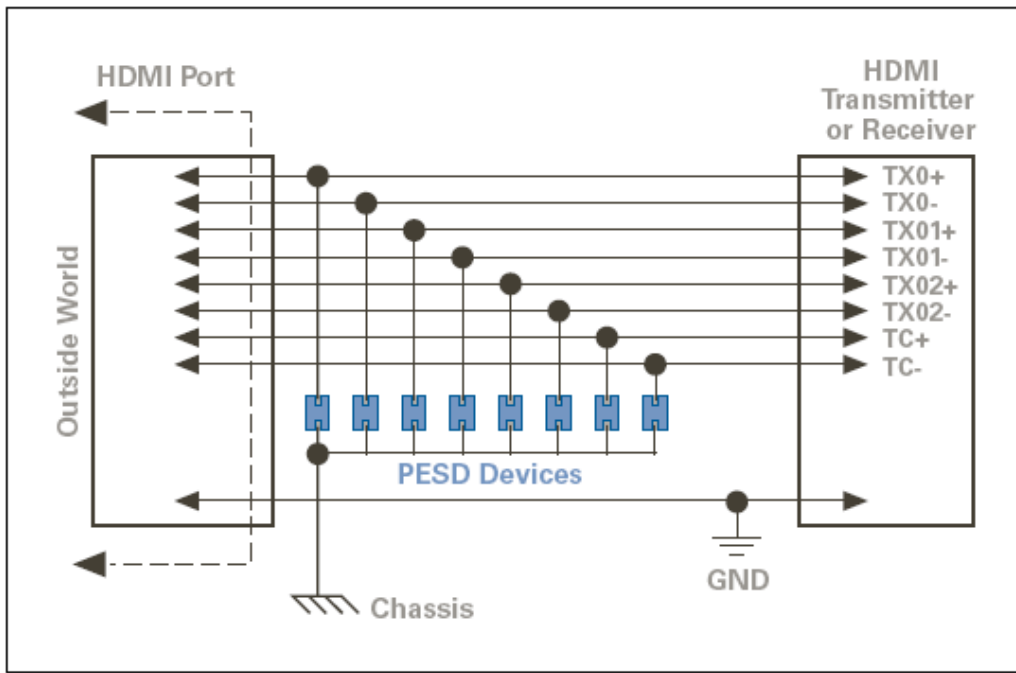
**FIG 3: INSERTION LOSS DIAGRAM (TYPICAL SAMPLE)**

(PESD0402 Minimal Insertion Loss at 3.4 GHz)



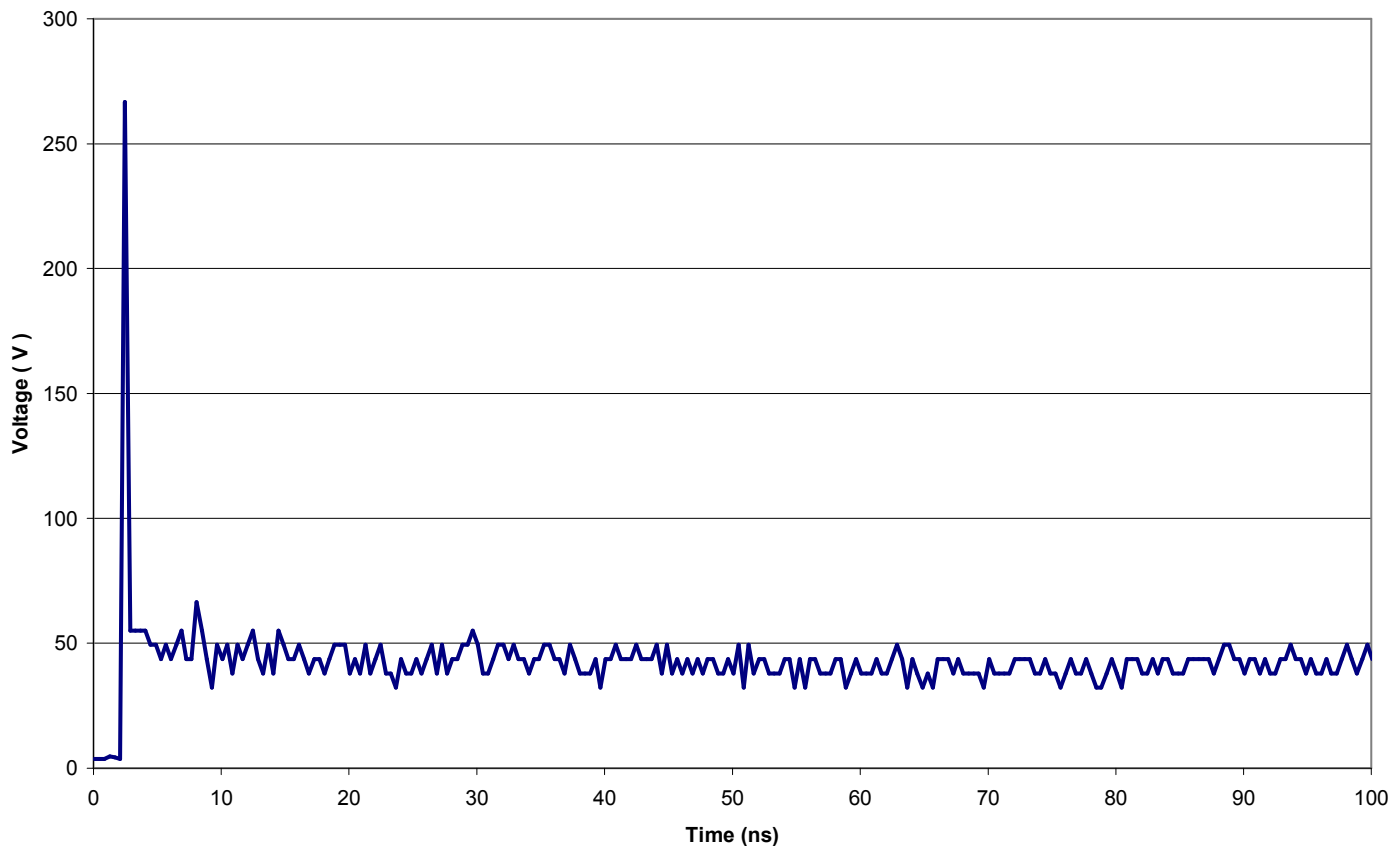
**FIG 4: ESD PROTECTION FOR HDMI**

(PESD0402 Reference Layout and Test Results available)



**FIG 5: TYPICAL TRANSMISSION LINE PULSE RESPONSE GRAPH**

**Typical TLP Clamping Voltage**

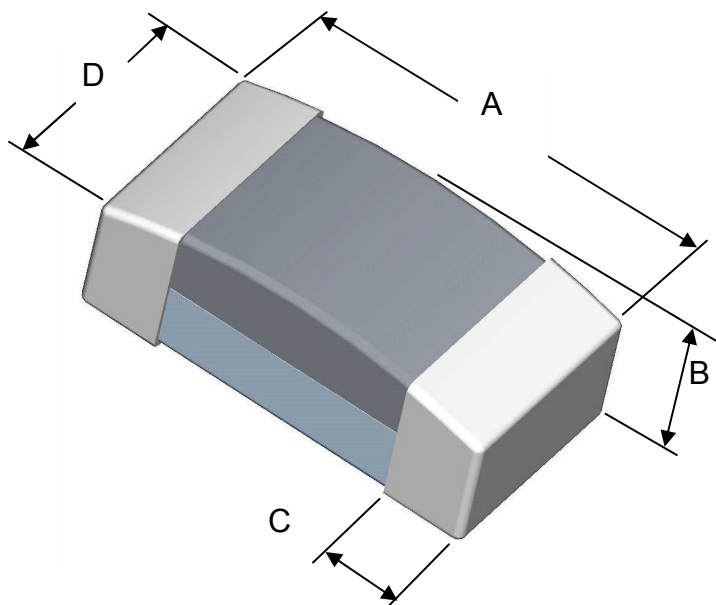


## ESD Protector Overvoltage Protection Device

**PRODUCT: PESD0402-140**

DOCUMENT: SCD27440  
REV LETTER: D  
REV DATE: MAY 10, 2011  
PAGE NO.: 6 OF 9

### DIMENSIONS



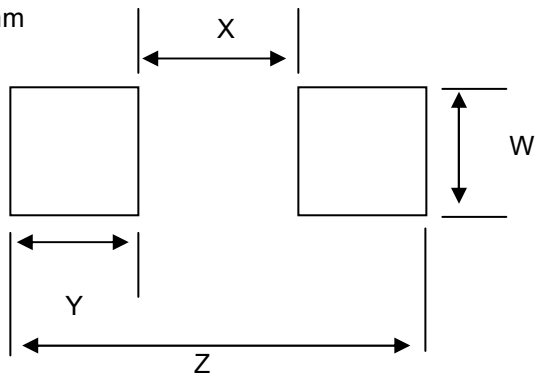
Drawing Not To Scale

	Length A		Height B		Terminal Width C		Width D	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	0.90	1.10	0.23	0.43	0.10	0.30	0.40	0.60
in*	(0.035)	(0.043)	(0.009)	(0.017)	(0.004)	(0.012)	(0.016)	(0.024)

\* Round off approximation

### RECOMMENDED LAND PATTERN:

Solder thickness 0.15 to 0.2mm



	W		X		Y		Z	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	0.60	0.70	0.30	0.40	0.80	0.90	2.10	2.20
in*	(0.024)	(0.028)	(0.012)	(0.016)	(0.031)	(0.035)	(0.083)	(0.087)

\* Round off approximation

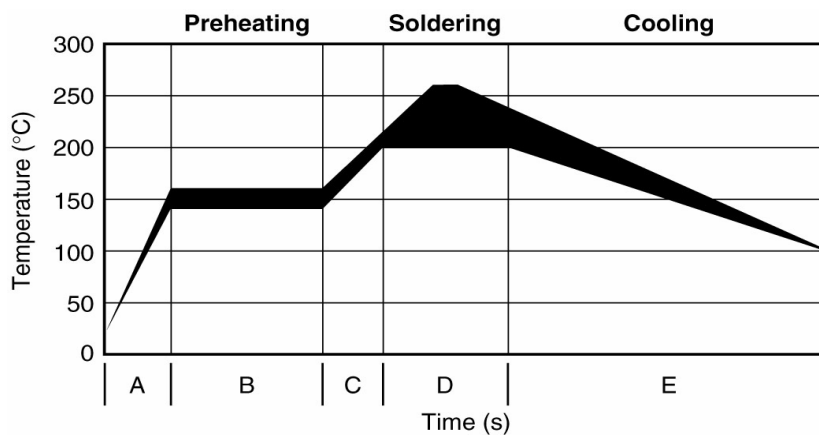
## ESD Protector Overvoltage Protection Device

**PRODUCT: PESD0402-140**

DOCUMENT: SCD27440  
REV LETTER: D  
REV DATE: MAY 10, 2011  
PAGE NO.: 7 OF 9

### SOLDER REFLOW RECOMMENDATIONS:

A	Temperature ramp up 1	From ambient to Preheating temperature	30s to 60s
B	Preheating	140°C - 160°C	60s to 120s
C	Temperature ramp up 2	From Preheating to Main heating temperature	20s to 40s
D	Main heating	at 200°C at 220°C at 240°C at 260°C	60s ~ 70s 50s ~ 60s 30s ~ 40s 5s ~ 10s
E	Cooling	From main heating temperature to 100°C	4°C/s (max)



## ESD Protector Overvoltage Protection Device

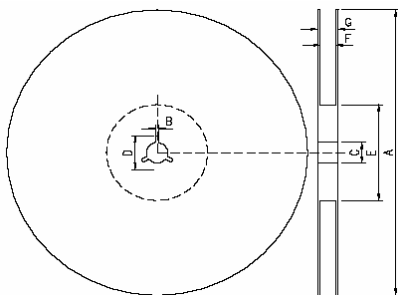
**PRODUCT: PESD0402-140**

DOCUMENT: SCD27440  
REV LETTER: D  
REV DATE: MAY 10, 2011  
PAGE NO.: 8 OF 9

### PACKAGING

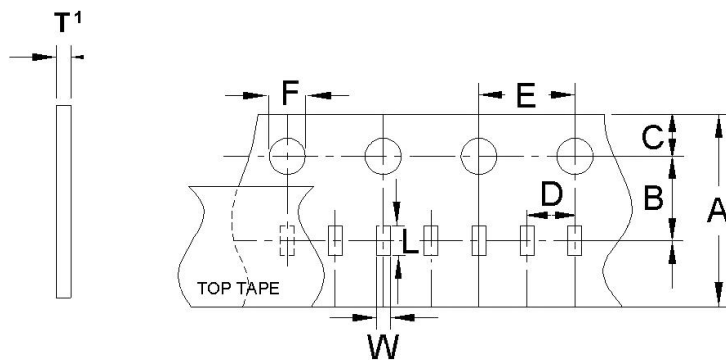
Packaging	Tape & Reel	Standard Box
PESD0402-140	10,000	50,000

#### EIA referenced Reel Dimensions for PESD Devices



#### Reel Dimensions (mm):

	A	B	C	D	E	F	G
<b>0402 Devices</b>	178.0 ±2.0	2.0 ±0.5	13.0 ±0.5	21.0 ±0.8	62.0 ±1.5	9.0 ±0.5	13.0 ±1.0



#### Carrier Dimensions (mm):

	A	B	C	D	E	F	L	W	T <sup>1</sup>
<b>0402 Devices</b>	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 ±0.1	1.19 ±0.05	0.69 ±0.05	0.48 ±0.03

Note 1: Carrier thickness

**Product Orientation** – always face up (meaning the substrate is at the bottom), but parts do not have polarity mark.

**Leader & Trailer:** The leader is 180mm in length & consists of empty cavities with sealed cover tape.  
The trailer is 350mm in length & consists of empty cavities with sealed cover tape.



## POST REFLOW, CLEANING CONDITIONS

A 5% saponifier combined with water during wash.

For the ultrasonic process water temperature should be at 50°C and board should be submerged for a minimum of one minute in the solutions, then rinse and dry.

For in-line washing, the temperature of the water sprayed should be at 110°C, rinse and drying is done in-line.



### **WARNING**

**Warning: Application Limitations for PESD0402-140. This part is not intended to be used on power lines or for power bus applications. Users should independently evaluate the suitability of and test each product selected for their own applications**

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of each product for their applications. Tyco Electronics Corporation and/or its Affiliates in the TE Connectivity Ltd. family of companies ("TE") reserves the right to change or update, without notice, any information contained in this publication; to change, without notice, the design, construction, processing, or specification of any product; and to discontinue or limit production or distribution of any product. This publication supersedes and replaces all information previously supplied. Without expressed or written consent by an officer of TE, TE does not authorize the use of any of its products as components in nuclear facility applications, aerospace, or in critical life support devices or systems. TE only obligations are those in the TE Standard Terms and Conditions of Sale and in no case will TE be liable for any incidental, indirect, or consequential damages arising from the sale, resale, use, or misuse of its products.

**HDMI** is a trademark of **HDMI Licensing LLC**

**Bluetooth** is a trademark of **Bluetooth SIG**

**TE Connectivity, TE Connectivity (logo) and TE (logo)** are trademarks